IPC ASSOCIATION CON ELECTRONICS INC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier In	nformation								,						
Company nan	ne*	Company unique ID			J	Unique ID Authority				Response Date*					
nsemi											2024-04-26				
Contact Name	e		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-	-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com					
authorized Re	epresentative*	Title - Representative			F	Phone - Representative*				Email - Representative*					
Product-Env-	-Stewards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
Re	equester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version Manufacturing Site		We	ight*	UOM	Unit Type		
		FDC86244 FET 150V 144.0 mOhm		Ohm SSOT6		2024-04-26		N	MY1		367	mg	Each		
	ring Process Informa		·	A11	CTD 020 MCI	Datin -	Deels Dee	De des Te		Man Time at Peals	T	Name	and Darkland Court	1	
2 -		-		STD-020 MSL	. Rating		ess Body 16	Body Temperature Max Time at Peak C 30				er of Reflow Cyc	eles		
•	atte Tin (Sn) - annealed	C	CU Alloy	1			260		IC.	30	seconds	3			
omments			1 10.2	20											
	mum time at peak temperat	8													
r more info	rmation regarding materia	I composition	piease refer t	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale appl											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.172	mg	Supplier	Silicon (Si)	7440-21-3		0.172	mg
Die Attach	0.203	mg		Epoxy resin	proprietary data		0.0203	mg
			Supplier	Silver (Ag)	7440-22-4		0.1624	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0203	mg
Lead Frame	8.254	mg	Supplier	Silver (Ag)	7440-22-4		0.022	mg
			Supplier	Zinc (Zn)	7440-66-6		0.01	mg
			Supplier	Iron (Fe)	7439-89-6		0.198	mg
			Supplier	Copper (Cu)	7440-50-8		8.022	mg
			Supplier	Phosphorus (P)	7723-14-0		0.002	mg
Mold Compound-Black	7.596	mg		Epoxy resin	proprietary data		0.3798	mg
			Supplier	Phenolic Resin	Proprietary Data		0.3798	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1519	mg
			Supplier	Carbon Black (C)	1333-86-4		0.038	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.6465	mg
Plating	1.13	mg	Supplier	Tin (Sn)	7440-31-5		1.13	mg
Wire Bond - Cu	0.012	mg	Supplier	Copper (Cu)	7440-50-8		0.012	mg